What is claimed is:

1. A bond pad for a flip chip package, suitable for an integrated circuit chip, comprising:

at least one slot extending along a direction which is perpendicular to a radial direction from the center of the integrated circuit chip.

2. The bond pad as claimed in claim 1, wherein the bond pad is located substantially at corners of the integrated circuit chip.

3. The bond pad as claimed in claim 1, wherein the patterns are arranged substantially in an array.

4. The bond pad as claimed in claim 1, wherein the bond pad is circular or rectangular.

5. The bond pad as claimed in claim 1, wherein the slot is rectangular.

6. The bond pad as claimed in claim 1, wherein the slot extends at least partially through the bond pad.

7. The bond pad as claimed in claim 1, wherein the slot extends down to the bottom of the bond pad.

8. A bond pad for a flip chip package, suitable for an integrated circuit chip, comprising:

a plurality of parallel slots located in the bond pad, each of the slots extending along a direction which is perpendicular to a radial direction from the center of the integrated

circuit chip, wherein the bond pad deposed at the corner of the integrated circuit chip.

9. The bond pad as claimed in claim 8, wherein the bond pad is circular or rectangular.

10. The bond pad as claimed in claim 8, wherein the slot is rectangular.

11. The bond pad as claimed in claim 8, wherein the slot extends at least partially through the bond pad.

12. The bond pad as claimed in claim 8, wherein the slot extends down to the bottom of the bond pad.

13. A bond pad structure for a flip chip package, suitable for an integrated circuit chip, the integrated circuit chip having a rectangular shape, comprising:

a plurality of bond pads located in each of the quadrants of the integrated circuit chip, wherein each of the bond pads comprises at least one slot and each of the slots in the same quadrant extending along a direction which is substantially perpendicular to the diagonal lines of the integrated circuit chip passing through the quadrant in which it is located.

14. The bond pad as claimed in claim 13, wherein the patterns are arranged substantially in an array.

15. The bond pad as claimed in claim 13, wherein the slot is rectangular.

16. The bond pad as claimed in claim 13, wherein the slot extends at least partially through the bond pad.

17. The bond pad as claimed in claim 13, wherein the slot extends down to the bottom of the bond pad.

18. The bond pad as claimed in claim 13, wherein the bond pad is circular or rectangular.

19. A semiconductor device, comprising:

a substrate;

a conductive layer, disposed on the substrate; and

at least one bond pad, disposed on the conductive layer, wherein the bond pad comprises at least one slot extending along a direction which is perpendicular to a radial direction from the center of the surface of the substrate.

20. The bond pad as claimed in claim 19, wherein the number of the bond pad located in the quadrants of the integrated circuit chip is more than one, and each of the slots in the same quadrant extending along a direction which is substantially perpendicular to the diagonal lines of the integrated circuit chip passing through the quadrant in which it is located.

21. The bond pad as claimed in claim 19, wherein the slot is rectangular.

22. The bond pad as claimed in claim 19, wherein the slot extends at least partially through the bond pad.

23. The bond pad as claimed in claim 19, wherein the slot extends down to the bottom of the bond pad.